

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

**Claim 1 (cancelled)**

1           **Claim 2 (currently amended):** The electronic component  
2       mounting method according to claim 5 [[1]], further  
3       comprising the step of:  
4               feed-forward controlling a detected result of the  
5       printing position of the solder paste from the step of  
6       detecting to the step of mounting,  
7               wherein the detected result is an output at the step  
8       of detecting.

**Claims 3-4 (cancelled)**

1           **Claim 5 (currently amended):** An electronic component  
mounting method for mounting an electronic component The  
electronic component mounting method according to claim 1,  
4       further comprising the steps of:  
5               providing a circuit board further comprising a land;  
6       dividing the circuit board into a plurality of blocks;  
7       printing a solder paste on the land;

8           detecting a printing position of the solder paste on  
9           the circuit board;

10           mounting the electronic component on the circuit board  
11           by referring to the printing position of the solder paste  
12           as a reference;

13           obtaining a shift amount between a position of the  
14           land corresponding to the electronic component to be  
15           mounted in each block and the printing position of the  
16           solder paste for the land; and

17           setting a target mounting position of the electronic  
18           component for each block based on the shift amount thus  
19           obtained.

1           Claim 6 (original): The electronic component mounting  
2           method according to claim 5,

3           wherein the blocks are obtained by an annular division  
4           from a peripheral edge of the circuit board toward a  
5           center.

1           Claim 7 (original): The electronic component mounting  
2           method according to claim 5,

3           wherein the blocks are obtained by dividing the  
4           circuit board like a lattice.

1                   Claim 8 (currently amended): An electronic component  
2                   mounting method for mounting an electronic component ~~The~~  
3                   electronic component mounting method according to claim 1,  
4                   further comprising the steps of:  
5                   providing a circuit board further comprising a land;  
6                   printing a solder paste on the land;  
7                   detecting a printing position of the solder paste on  
8                   the circuit board;  
9                   mounting the electronic component on the circuit board  
10                  by referring to the printing position of the solder paste  
11                  as a reference;  
12                  deciding a self-alignment effect from a shift state  
13                  between a position of a land corresponding to the  
14                  electronic component to be mounted and the printing  
15                  position of the solder paste for the land;  
16                  setting a target mounting position of the electronic  
17                  component by using the printing position of the solder  
18                  paste as a reference in a case that the self-alignment  
19                  effect is great; and  
20                  setting the target mounting position by using the  
21                  position of the land as the reference in a case that the  
22                  self-alignment effect is small.

1                   Claim 9 (currently amended): An electronic component  
2                   mounting method for mounting an electronic component ~~The~~  
3                   electronic component mounting method according to claim 1,  
4                   further comprising the steps of:

5                   providing a circuit board further comprising a land;  
6                   printing a solder paste on the land;  
7                   detecting a printing position of the solder paste on  
8                   the circuit board;  
9                   mounting the electronic component on the circuit board  
10                   by referring to the printing position of the solder paste  
11                   as a reference;

12                   setting a correction value at an optional rate for a  
13                   shift amount between a position of a land corresponding to  
14                   the electronic component to be mounted and the printing  
15                   position of the solder paste for the land; and

16                   changing a target mounting position of the electronic  
17                   component from the position of the land toward the printing  
18                   position of the solder paste based on the correction value  
19                   thus set.

1                   Claim 10 (original):    The electronic component  
2                   mounting method according to claim 9,  
3                   wherein the correction value is set based on a degree  
4                   of the self-alignment effect which is determined depending

5 on a shift state between the position of the land  
6 corresponding to an electronic component to be mounted and  
7 the printing position of the solder paste for the land.

1           Claim 11 (original):    The electronic component  
2 mounting method according to claim 9,  
3            wherein the correction value is set depending on a  
4 characteristic of a solder paste to be used.

1           Claim 12 (currently amended):   The electronic  
2 component mounting method according to claim 8 [[1]],  
3            wherein the step of mounting is not carried out in the  
4 case that the electronic component interferes with adjacent  
5 other electronic components on the circuit board.

1           Claim 13 (currently amended):   The electronic  
2 component mounting method according to claim 8 [[1]],  
3 further comprising the step of:

4            changing the a target mounting position of the  
5 electronic component to be mounted toward the position of  
6 the land and from the printing position of the solder paste  
7 to a position in which the interference is not present in  
8 the case that the electronic component interferes with  
9 adjacent other electronic components on the circuit board.

1           Claim 14 (currently amended): An electronic component  
2       mounting method for mounting an electronic component The  
3       electronic component mounting method according to claim 1,  
4       further comprising the steps of:

5       providing a circuit board further comprising a land;  
6       dividing the circuit board into a plurality of blocks;  
7       printing a solder paste on the land;  
8       detecting a printing position of the solder paste on  
9       the circuit board;

10       mounting the electronic component on the circuit board  
11       by referring to the printing position of the solder paste  
12       as a reference;

13           obtaining a shift amount in a direction of rotation  
14       and a shift amount in a horizontal direction in the case  
15       that a shift amount of a position of the land corresponding  
16       to the electronic component to be mounted from the printing  
17       position of the solder paste for the land exceeds a  
18       predetermined shift amount, and

19           setting a target mounting position and a target  
20       rotating angle of the electronic component based on the  
21       shift amounts in the horizontal direction and the direction  
22       of rotation.

1                   Claim 15 (currently amended):     The electronic  
2                   component mounting method according to claim 8 [[1]],  
3                   wherein the step of detecting includes the steps of:  
4                   picking up an image of a circuit board having a solder  
5                   paste printed thereon;  
6                   reproducing a shape of a land hidden in the solder  
7                   paste by interpolating the picked-up image with referring  
8                   previously registered land data; and  
9                   obtaining a center of a position of the land from the  
10                  shape of the land thus reproduced.

Claims 16-30 (cancelled)